PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	MDG/17/10568
1.3 Title of PCI	New Tape Header finishing procedure for EEPROM in WLCSP (packed with EPE foam)
1.4 Product Category	EEPROM in WLCSP
1.5 Issue date	2017-11-21

2. PCI Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Benoit RODRIGUES
2.1.2 Marketing Manager	Hubert LEDUC
2.1.3 Quality Manager	Rita PAVANO

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Process flow chart: Revision change in Process/Recipe like addition, deletion of process step (process technology, sawing, die attach, plasma, marking, packing, labelling, transportation, etc..)	STATSChipPAC subcontractor

4. Description of change		
	Old	New
4.1 Description	- In the current situation, the header is linked to the EPE foam, which is linked to the protective belt. Then placing (at finishing step) or removing (at customer unreeling step) the protective belt could induce tension to the tape.	With the new procedure, the header is pasted to itself (with ESD tape). The EPE foam is put in place and pasted to the protective belt. Then, the protective belt and the header being independent, removing the protective belt will have no action on the tape.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change	
5.1 Motivation	Reduction of potential tight winding of the tape.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	N/A

7. Timing / schedule	
7.1 Date of qualification results	2017-11-20
7.2 Intended start of delivery	2017-12-11
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation	
8.1 Description	

8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)
10568 Public product.pdf 10568 PCI End of Tape WLCSP ALL CUSTOMERS WITH EPE -1-.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128-DFCS6TP/K	
	M24128S-FCU6T/T	
	M24256-DFCS6TP/K	
	M24512-DFCS6TP/K	
	M24C16-DFCU6TP/K	
	M24C32S-FCU6T/T	
	M24C64-DFCT6TP/K	
	M24C64-FCS6TP/K	
	M24C64S-FCU6T/T	
	M24M01-DFCS6TP/K	
	M24M02-DRCS6TP/K	
	M95128-DFCS6TP/K	
	M95256-DFCS6TP/K	
	M95512-DFCS6TP/K	
	M95M01-DFCS6TP/K	
	M95M02-DRCS6TP/K	

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